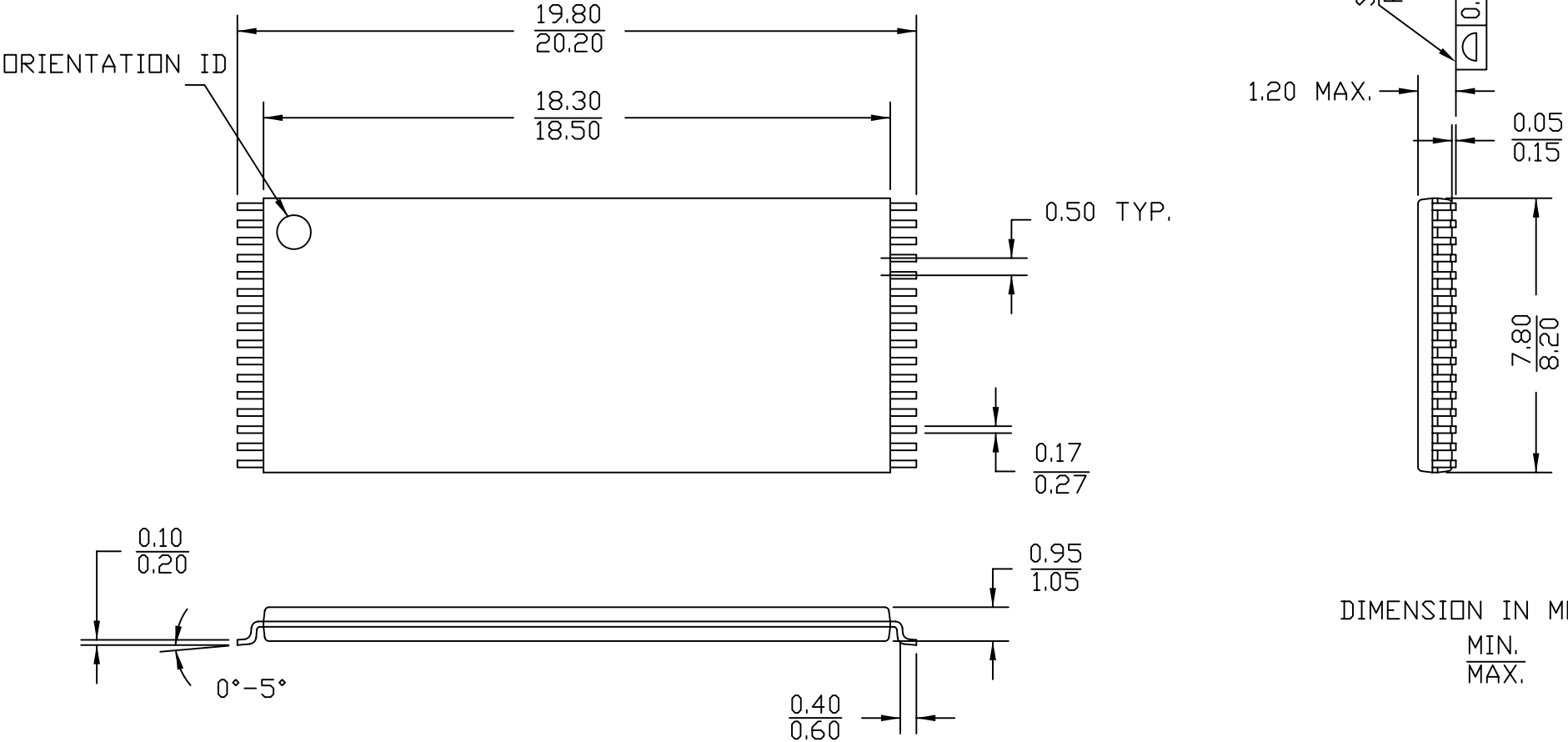


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	689	NEW RELEASE	01/25/94	N/A
1	-	*A	47126	CHG. DIM. ON LEAD WIDTH, STAND OFF. CHG. TITLE	11/01/96	N/A
1	-	*B	49405	CHG. TITLE/ ADD LEAD COPLANARITY	06/11/97	N/A
1	-	*C	66392	REMOVE THE INCH UNIT ON DIMENSIONS	02/17/00	N/A
1	-	*D	103906	REMOVE PIN NUMBER	11/20/00	N/A
1	-	*E	2851411	Changed template, & title from 32LD (8X20MM) TSOP I PKG OUTLINE to PACKAGE OUTLINE, 32LD TSOP I 8X20X1.0 MM Z32.	01/15/10	QAD

# 32 Lead TSOP I 8 X 20 mm - STANDARD



DIMENSION IN MM  
MIN.  
MAX.

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	DRAWN BY	HTN	DATE	11/20/00	
	CHECKED BY	TSV	DATE	1/15/10	
	APPROVED BY	QAD	DATE	1/15/10	
MATERIAL	N/A	APPROVED BY	JGUA	DATE	1/15/10
FINISH	N/A	APPROVED BY	N/A	DATE	N/A

CYPRESS Company Confidential			
TITLE PACKAGE OUTLINE, 32LD TSOP I 8X20X1.0 MM Z32			
SIZE	PART NO.	DWG NO	REV
A	Z32	51-85056	*E
SCALED TO FIT	N/A	SHEET	10F 1